Information & Control Korea TC Chapter

Meeting Summary and Minutes

October 7 2016, 14:00 – 17:00

#4205 Trade Tower 511, Yeongdong-daero, Gangnam-gu, Seoul, Korea

TC Chapter Announcements

Advanced Backend Factory Integration task force is approved.

Next TC Chapter Meeting

February 9, 2017 10:00 – 12:00

Room 305 3FL., Conference Center (Soundh), Coex, Seoul, Korea

**Table 1 Meeting Attendees**

*Italics* indicate virtual participants

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<th>Company</th>
<th>Last</th>
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<tbody>
<tr>
<td>AIM</td>
<td>Jung</td>
<td>Jinsoo</td>
<td>Linkgenesis</td>
<td>Kim</td>
<td>Byeonghee</td>
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<tr>
<td>ASM</td>
<td>Jung</td>
<td>Il Gun</td>
<td>Linkgenesis</td>
<td>Paek</td>
<td>Inhyeok</td>
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<tr>
<td>ASM</td>
<td>Shim</td>
<td>Jongsuh</td>
<td>SEMES</td>
<td>Cho</td>
<td>Changyul</td>
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<td>Doople</td>
<td>Kim</td>
<td>Hyungsu</td>
<td>SK hynix</td>
<td>Ahn</td>
<td>Chulhong</td>
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<td>Hanmi Semiconductor</td>
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<td>Youngjang</td>
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<td>Park</td>
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<td>Kornic Automation</td>
<td>Kim</td>
<td>Kyung Tae</td>
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<td>Linkgenesis</td>
<td>Cha</td>
<td>Kyounghwan</td>
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**Table 2 Leadership Changes**

Youngshin Lim is appointed as Advanced Backend Factory Integration task force leader.

**Table 3 Ballot Results**

None

**Table 4 Authorized Activities**

<table>
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<tr>
<th>#</th>
<th>Type</th>
<th>SC/TF/WG</th>
<th>Details</th>
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</thead>
<tbody>
<tr>
<td>TFOF</td>
<td>ABDI TF</td>
<td></td>
<td>Advanced Backend Factory Integration task force newly formed</td>
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NOTE 1: SNARFs and TFOFs are available for review on the SEMI Web site at: [http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF](http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF)
1 Welcome, Reminders, and Introductions

Chulhong Ahn (SK hynix) called the meeting to order at 14:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves. Two new members, Youngjang Lim (Hanmi semiconductor) and Minhee Park (SK hynix) were also introduced.

Attachment: 01, Meeting Reminders

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Approve the previous meeting minutes as it is
By / 2nd: Jongsub Shim (ASM)/ ChangYul Cho (SEMES)
Discussion: None
Vote: 8-0, Motion Carried

Attachment: 02, Previous Meeting Minutes

3 Liaison Reports

3.1 Information & Control Japan TC Chapter
Natalie Shim (SEMI Korea) reported for the I&C Japan TC Chapter. Of note:

- Leadership and Structure Change
  - No change
- Document Review Summary
  - Passed (Cycle 4, 2016)
    - 5601A (New Standard, Specification for Wafer Job Management (WJM))
    - 6034 (Reapproval of SEMI E54.21-1110, Specification for Sensor Actuator Network for MOTIONNET® Communication)
    - 6035 (Line Item Revision to SEMI E91-0600 (Reapproved 1109), Specification for Prober Specific Equipment Model (PSEM))
    - 6036 (Reapproval of SEMI E153-0310, Specification for AMHS SEM (AMHS SEM))
    - 5973 (Line Item Revision to SEMI E170-0416, Specification for Secured Foundation of Recipe Management System (SFORMS) and SEMI E170.1-0416, Specification for SECS-II Protocol for Secured Foundation of Recipe Management System)
- Upcoming ballots for cycle 7, 2016
  - 6033 (New Standard, Specification for Wafer Job Management, WJM))
- Announcement
  - SEMI E170, SEMI E171 and #5601 document group was named “GEM300A”.
  - STEP/GEM300A to be held on Friday, May 20, 13:00-18:30 at SEMI Japan office
- Equipment System Security (EISS) TF
  - Discussed the SNARF for Access Control
    - No consensus has been reached
    - Decided to suspend the discussion
  - Proposal from GEM300 TF
    - To define Access Control in GEM300A architecture.
    - Agreed to endorse GEM300 TF proposal.
- Fiducial Mark Interoperability TF
  - 5890 (Revision to SEMI T7-0415 Specification for back surface marking of double-side polished wafers with a two-dimensional matrix code symbol)
    - Ballot was passed with editorial changes at Japan TC Chapter meeting of Traceability GTC in conjunction with SEMICON Japan 2015 held on December 18 and also passed A&R. The document is waiting for the publication.
  - Assembly and Packaging: Discussing backend alignment issues with introducing fiducial mark wafer.
  - Task force leaders to start discussion about disbanding this TF if the TF doesn’t have further activity.
- GEM 300 TF
  - New activity proposal
TF consider to propose new standard “CUARAM: Centralized User Authentication & Role Authorization Management”. The scope was discussed with EISS TF and SNARF is scheduled to submit for the next TC Chapter meeting.

According to comment from potential Standards users at GEM300A STEP, TF consider to revise E170.1, E171 and E5 by simplifying each subordinate standard by using dedicated SECS II message, instead of OSS generic service. Assumed stream number for E170.1 is S20, and E171.1 is S21. SNARF is scheduled to submit for the next TC Chapter meeting.

- 5618 (New Standard, Specification for Preservation of Recipe Integrity (PRI))
  - TF decided to give up the 5618 activity which is owned by NA TC Chapter.

- Japan I&C Committee Maintenance TF
  - SNARF 5615 (SEMI E98&E98.1 (OBEM)) was withdrawal.
  - 6036 (Reapproval of SEMI E153 (AMHS SEM)): SNARF and ballot were submitted for Cycle 7.
  - 6033 (Line Item Revision to SEMI E99 and E99.1 (Carrier ID Reader/Writer)): SNARF and ballot were submitted for Cycle 7.
  - 6034 (Reapproval of SEMI E54.21 (MOTIONNET®)): SNARF and ballot were submitted for Cycle 7.
  - 6035 (Line Item Revision to SEMI E91 (PSEM)): SNARF and ballot were submitted for Cycle 7 but the ballot is postponed.
  - No further action for the SEMI E107 (Specification of Electric Failure Link Data Format for Yield Management System).

- Next meeting: Friday, October 21, 2016 at SEMI Japan office, Tokyo

**Action Item 1:** Share CUARAM SNARF with Korea I&C members

**Attachment:** 03, Japan Liaison report

### 3.2 Information & Control North America TC Chapter

Natalie Shim reported for the I&C NA TC Chapter. Of note:

- Leadership and Structure Change
  - Gino Crispieri stepped down from ESEC TF, GEM300 TF and DDA TF
  - Andreas Neuber (AMAT) appointed as new ESEC TF leader

- Document Review Summary (Reviewed in NA Summer Meeting)
  - **Passed**
    - 5821C (New Standard, Specification for Subsystem Energy Savings Mode Communication (SESMC))
    - 5912A (Line Item Revisions to E142.1-0211, XML Schema for Substrate Mapping, E142.2-0211, SECS II Protocol for Substrate Mapping, and E142.3-0211, Web Services for Substrate Mapping, to correct nonconforming titles)
    - 6020 (Line Item revision to SEMI E30.1-0309, INSPECTION AND REVIEW SPECIFIC EQUIPMENT MODEL (ISEM) to correct nonconforming title)
    - 6021 (Line Item revision TO SEMI E123-0703 (REAPPROVED 1109), STANDARD FOR HANDLER EQUIPMENT SPECIFIC EQUIPMENT MODEL (HSEM) to correct nonconforming title)
- 6022 (Line Item revision to SEMI E138-0709, XML SEMICONDUCTOR COMMON COMPONENTS to correct nonconforming title)
- 6023 (Line item revision to SEMI E122, STANDARD FOR TESTER EQUIPMENT SPECIFIC EQUIPMENT MODEL (TSEM) to correct nonconforming title)
- 6024 (Reapproval of SEMI E30.5, SPECIFICATION FOR METROLOGY SPECIFIC EQUIPMENT MODEL (MSEM))
- 6025 (Reapproval of SEMI E142, SPECIFICATION FOR SUBSTRATE MAPPING)
  o Failed
  - 5549 (Revision to SEMI E30, Generic Model for Communications and Control of Manufacturing (GEM) for Title Change; Specification for the Generic Model for Communications and Control of Manufacturing (GEM))
  - 5872 (Line Item Revisions to E171, Specification for SECS Equipment Data Dictionary (SEDD))
- Upcoming ballots for cycle 6 and 7, 2016
  o R5821C (New Standard, Specification for Energy Savings Mode Communication between Semiconductor Equipment and Sub-Systems)
  o 5872A (Line Item Revisions to SEMI E172, Specification for SECS Equipment Data Dictionary (SEDD)
  o 6026 (Reapproval of SEMI E109-1110, Specification for Reticle and Pod Management (RPMS))
  o 6038 (Reapproval of SEMI E160-1211, Specification for Communication of Data Quality)
  o 6064 (Reapproval for SEMI E121-0305, Guide for Style and Usage of XML for Semiconductor Manufacturing Applications)
  o And 13 more for 5-year review.
- SNARF 3 Year Status
  o 5589 (Revision to E5, E40.1, E90.1, E94.1, E109, E109.1, E116.1) is abolished.
  o 5618 (New Standard, Specification for Preservation of Recipe Integrity) is abolished.
  o 5549 (Revision to SEMI E30, Generic Model for Communications and Control of Manufacturing Equipment, GEM) is extended for a year.
- Next Meetings are scheduled on November 7 to 9, 2016 at SEMI HQ

**Action Item 2:** Keep members update about EDA Freeze 3 development status. (Hyungsu Kim & Natalie Shim)

**Attachment:** 04, North America Liaison report

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### 3.3 Information & Control Taiwan TC Chapter

Natalie Shim reported for the Information & Control Taiwan TC Chapter. Of note:

- Leadership and Structure Change
  - None
- Backend Factory Integration TF
  - Completed the mandatory two-week SNARF review for “Specification of Backend Die Traceability” on April 27. Currently discussing those comments received from global I&C TC members.
- Printed Circuit Board Equipment Communication Interfaces (PCBECI) TF
  - The TF was newly approved on September 9.
SNARF (New Standard, Guide for PCB Equipment Communication Interface (PCBECI)) was submitted for two-week review on September 23.

- Equipment Information Integration TF
  - No Activity
- GEM300 TF
  - No Activity

**Attachment:** 05, Taiwan Liaison report

### 3.4 SEMI Staff Report

Natalie Shim gave the SEMI Staff Report. The summary is as below.

- Critical Dates update
  - 2016 Critical dates including newly created cycle 9 is introduced. It also can be found at SEMI website (www.semi.org/en/Standards/P_000788)

- SEMI Standards Publications Report

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<tr>
<th>Cycle</th>
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- Total SEMI Standards in portfolio: 964 including 149 Inactive Standards
- SEMI’s perspective on Smart Manufacturing was presented. There will be a related forum (Feb 9, 2017) during SEMICON Korea 2017 as sequential global events.
- Re-organized Korean web page for Standards contents and newly developed mobile access page were also introduced.

**Attachment:** 06, SEMI Staff report

### 4 Ballot Review

None

### 5 Subcommittee and Task Force Reports

#### 5.1 GEM300 Task Force

Each project owner reported their issues. No written report provided.

- 5832 (New Standard, Specification for Generic Counter Model (GCM))
  - Ilgun Jung (ASM) shared the TF review result on draft. Additional comments from the committee will be reflected to the final draft. He will make pre-review request to other regions before the ballot submission.

**Motion:** Authorize 5832 in cycle 9, 2016

**By / 2nd:** Ilgun Jung (ASM)/ ChangYul Cho (SEMES)

**Discussion:** None

**Vote:** 10-0, Motion Carried
• 5833 (New Standard, Specification for Maintenance Program Model)
  ○ Hyungsu Kim reported that he need more time to review current scope.

**Action Item 3:** Ilgun Jung will make pre-review request to GEM300 TFs for 5832 draft before he submit the ballot for cycle 9.

### 6 New Business

#### 6.1 Advanced Back-end Factory Integration task force formation

Natalie Shim forwarded TFOF approval request for Youngshin Im (Miracom Inc) as he and the team members were not able to attend the meeting in person.

**Motion:** Approve Advanced Back-end Factory Integration (ADFI) task force  
**By / 2nd:** Ilgun Jung (ASM)/ Hyungsu Kim (Doople)  
**Discussion:** The committee strongly recommended that the TF need more members who can represent each suppliers chain in back-end side. Also committee requests the TF to share their specific plan by the next committee meeting.  
**Vote:** 10-0, Motion Carried

**Action Item 4:** Share the TF’s future plan in the next meeting scheduled on Feb 9, 2017

**Attachment 7:** TFOF for Advanced Back-end Factory Integration TF

### 7 Next Meeting and Adjournment

The next meeting is scheduled for February 9, 2017 at Ceox, Seoul in conjunction with SEMICON Korea 2017. See [http://www.semi.org/en/events](http://www.semi.org/en/events) for the current list of meeting schedules.

Having no further business, a motion was made to adjourn. Adjournment was at 17:00.

Respectfully submitted by:  
Natalie Shim  
Sr. Specialist, Standards  
SEMI Korea  
Phone: 82.2.531.7808  
Email: eshim@semi.org

Minutes approved by:

<table>
<thead>
<tr>
<th></th>
<th>Title</th>
<th>Date Approved</th>
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<tr>
<td>Chulhong Ahn (SK Hynix), Co-chair</td>
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<tr>
<td>Hyungsu Kim (Doople), Co-chair</td>
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<tr>
<td>Kevin Lee (Lam Research), Co-chair</td>
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**Table 8 Index of Available Attachments**

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<td>01, Meeting Reminders</td>
<td>05, Taiwan Liaison report</td>
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</tbody>
</table>
## Meeting Minutes

### 02. Previous Meeting Minutes

### 03. Japan Liaison report

### 04. North America Liaison report

### 06. SEMI Staff report

### 07. TFOF for Advanced Back-end Factory Integration TF

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.